

AMENDMENTS TO THE CLAIMS

Claim 1 (Previously Presented): A pressure sensor including
a semiconductor device capable of detecting pressure;
a bonding wire;
a terminal that is connected to the semiconductor device by the bonding wire;
a housing having an accommodation space accommodating the semiconductor device,
the bonding wire and the terminal;
a diaphragm sealing the accommodation space; and
a working fluid that is sealed in the accommodation space and transmits pressure
applied to the diaphragm to the semiconductor device, wherein
the working fluid is a silicone-based oil; and
the terminal and the housing are sealed by a fluorine-based adhesive to prevent
swelling of the adhesive.

Claim 2 (Currently Amended): A pressure sensor including
a semiconductor device capable of detecting pressure and in direct contact with the
environment outside of the sensor;
a bonding wire;
a terminal that is connected to the semiconductor device by the bonding wire; and
a housing having an accommodation space accommodating the semiconductor device,
the bonding wire and the terminal, wherein
the terminal and the housing are sealed by a fluorine-based adhesive.

Claim 3 (Original): The pressure sensor according to claim 1, wherein the fluorine-based adhesive is a perfluoro polyether resin composition.

Claim 4 (Original): The pressure sensor according to claim 2, wherein the fluorine-based adhesive is a perfluoro polyether resin composition.

Claim 5 (Previously Presented): The pressure sensor according to claim 2, wherein the pressure sensor does not include a working fluid.

Claim 6 (Previously Presented): A method of making a pressure sensor including a semiconductor device capable of detecting pressure; a bonding wire; a terminal that is connected to the semiconductor device by the bonding wire; a housing having an accommodation space accommodating the semiconductor device, the bonding wire and the terminal; a diaphragm sealing the accommodation space; and a working fluid that is sealed in the accommodation space and transmits pressure applied to the diaphragm to the semiconductor device, where the working fluid is a silicone-based oil; and the terminal and the housing are sealed by a fluorine-based adhesive, the method comprising sealing the terminal and the housing with the fluorine-base adhesive; and producing the pressure sensor of claim 1.

Claim 7 (Previously Presented): A method of making a pressure sensor including a semiconductor device capable of detecting pressure; a bonding wire; a terminal that is connected to the semiconductor device by the bonding wire; and a housing having an accommodation space accommodating the semiconductor device, the bonding wire and the terminal, where the terminal and the housing are sealed by a fluorine-based adhesive, the method comprising

sealing the terminal and the housing with the fluorine-based adhesive; and producing the pressure sensor of claim 2.